Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK2545

# DC-DC Converter, Relay Drive and Motor Drive Applications

• Low drain–source ON resistance :  $R_{DS}$  (ON) = 0.9  $\Omega$ (typ.)

• High forward transfer admittance :  $|Y_{fs}| = 5.5 \text{ S (typ.)}$ 

• Low leakage current :  $IDSS = 100 \mu A (max) (VDS = 600 V)$ 

• Enhancement-mode :  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

#### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	600	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		$V_{DGR}$	600	V	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1)	I <sub>D</sub>	6	Α	
	Pulse (Note 1)	I <sub>DP</sub>	24	Α	
Drain power dissipation	n (Tc = 25°C)	P <sub>D</sub>	40	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	345	mJ	
Avalanche current		I <sub>AR</sub>	6	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	4	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

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Weight: 1.9 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	3.125	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 16.8 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 6 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.



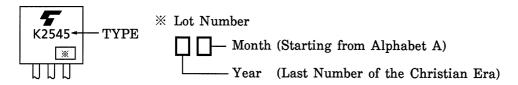
### **Electrical Characteristics (Ta = 25°C)**

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Gate-source bro	eakdown voltage	V <sub>(BR)</sub> GSS	$I_{G} = \pm 10 \ \mu A, \ V_{GS} = 0 \ V$	±30	_	_	٧
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 600 V, V <sub>DS</sub> = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V <sub>(BR) DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	600	_	_	٧
Gate threshold v	/oltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	٧
Drain-source O	N resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A	_	0.9	1.25	Ω
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3 A	2.0	5.5	_	S
Input capacitano	ce	C <sub>iss</sub>		_	1300	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	130	_	pF
Output capacitance		Coss		_	400	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} = \frac{10V}{0V} \int_{V_{OU}} V_{OU} dt$ $V_{GS} = \frac{10V}{0V} \int_{V_{OU}} R_{L} = 100\Omega$ $V_{DD} = 300V$ $Duty \le 1\%, t_{W} = 10\mu s$	_	25	_	- ns
	Turn-on time	t <sub>on</sub>		_	45	_	
	Fall time	t <sub>f</sub>		_	40	_	
	Turn-off time	t <sub>off</sub>		_	150	_	
Total gate charge (Gate-source plus gate-drain)		Qg			30	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$		18		nC
Gate-drain ("miller") charge		$Q_{gd}$		_	12	_	

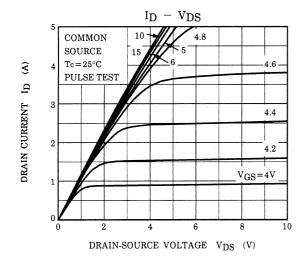
## Source-Drain Ratings and Characteristics (Ta = 25°C)

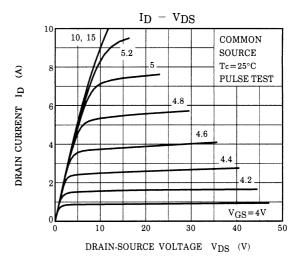
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	6	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	-	_	_	24	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 6 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 6 A, V <sub>GS</sub> = 0 V, dI <sub>DR</sub> / dt = 100 A / μs	_	1000		ns
Reverse recovery charge	Q <sub>rr</sub>	1DR - 0 Λ, VGS - 0 V, αιDR / αι - 100 Α / μs	_	7.0	_	μC

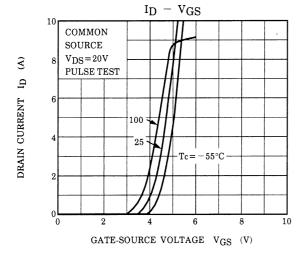
## Marking

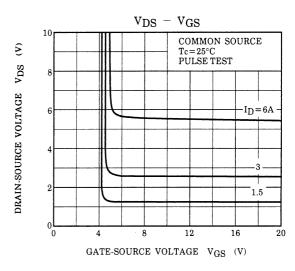


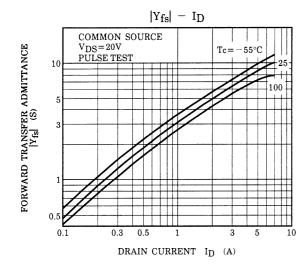
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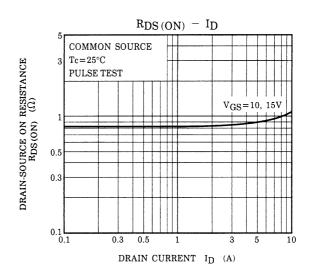


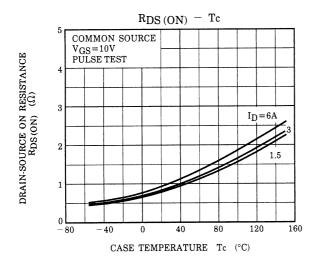


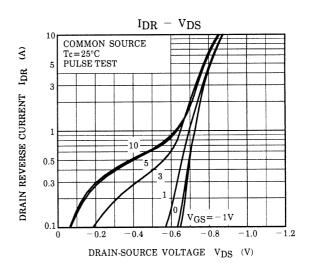


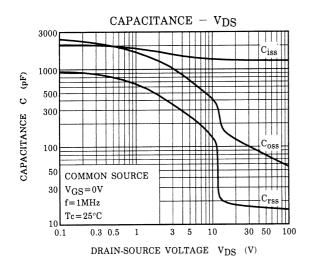


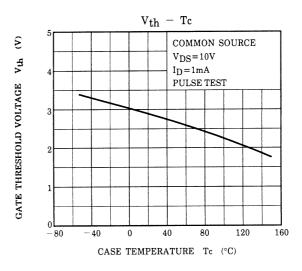


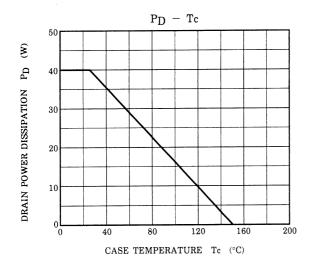


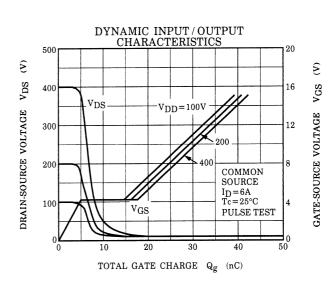


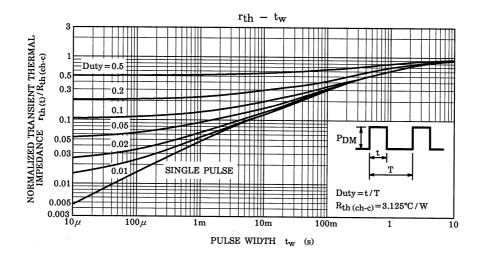


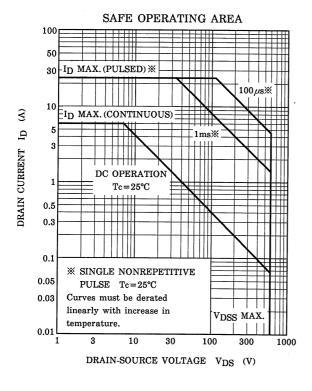


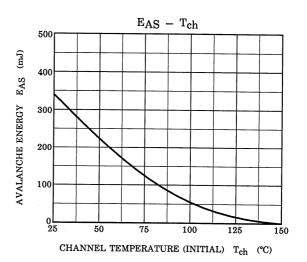


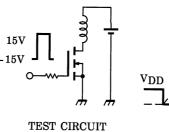


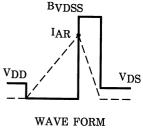












$$R_G$$
 = 25  $\Omega$   
 $V_{DD}$  = 90 V, L = 16.8 mH

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right)$$

#### **RESTRICTIONS ON PRODUCT USE**

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